

POLYHYDRIC PHENOL AND EPOXY RESIN OBTAINED
USING THE SAME

wherein R¹ independently represents a halogen atom, an alkyl or cycloalkyl group of 1-9 carbon atoms, an alkoxy group of 4 or less carbon atoms or an aryl group and R¹ may be identical or different when l is 2 or more, R² independently represents a halogen atom, an alkoxy group of 4 or less carbon atoms or an alkyl group of 6 or less carbon atoms and R² may be identical or different when m is 2 or more, R³ independently represents a hydrogen atom or an alkyl group of 6 or less carbon atoms, the average recurring unit number n is 0-10, l is 0-4 and m is 0-7, and can be contained as a curing agent in an epoxy resin composition which is used not only for giving cured

products but also for encapsulating semiconductor devices.

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